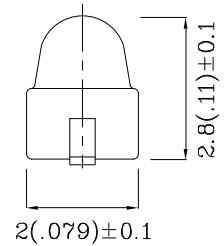
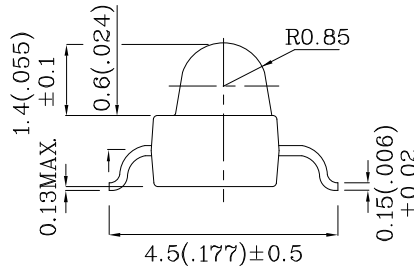
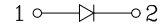
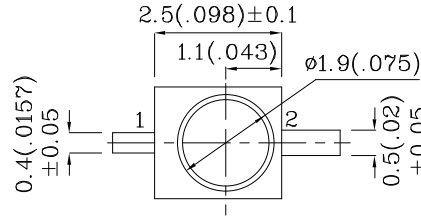


Features

- Subminiature package.
- Gull wing lead.
- Long life - solid state reliability.
- Low package profile.
- Package : 1000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES



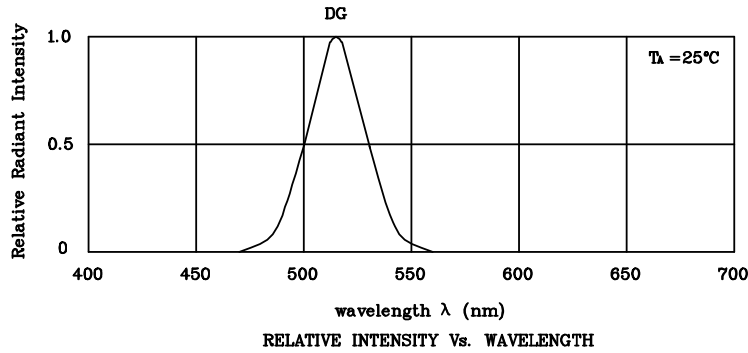
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ± 0.25(0.01") unless otherwise noted.
3. Specifications are subject to change without notice.

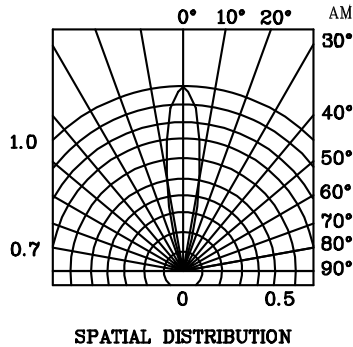
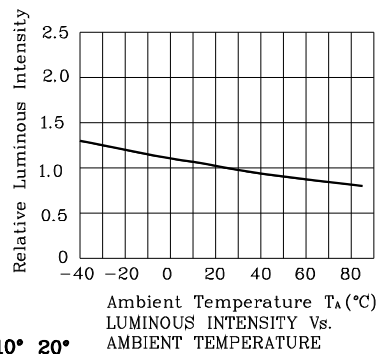
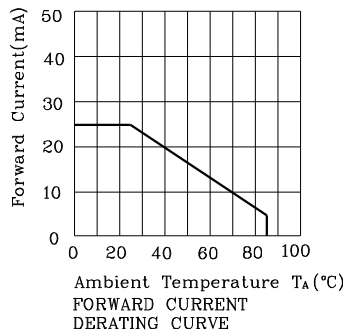
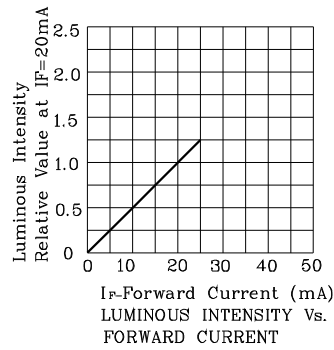
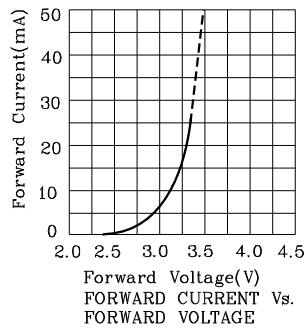
Absolute Maximum Ratings (TA=25°C)		DG (InGaN)	Unit
Reverse Voltage	V _R	5	V
Forward Current	I _F	25	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i _{FS}	150	mA
Power Dissipation	P _D	102.5	mW
Operating Temperature	T _A	-40 ~ +85	°C
Storage Temperature	T _{stg}	-40 ~ +85	

Operating Characteristics (TA=25°C)		DG (InGaN)	Unit
Forward Voltage (Typ.) (I _F =20mA)	V _F	3.3	V
Forward Voltage (Max.) (I _F =20mA)	V _F	4.1	V
Reverse Current (Max.) (V _R =5V)	I _R	50	uA
Wavelength of Peak Emission (Typ.) (I _F =20mA)	λ _P	515	nm
Wavelength of Dominant Emission (Typ.) (I _F =20mA)	λ _D	525	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	Δλ	30	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	C	45	pF

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (I _F =20mA) mcd		Wavelength nm λ _P	Viewing Angle 2θ 1/2
				min.	typ.		
XZDG46W-3	Green	InGaN	Water Clear	1200	2490	515	20°
Published Date : MAR 02,2010 Drawing No : XDSB4289 V1 Checked : B.L.LIU P.1/4							



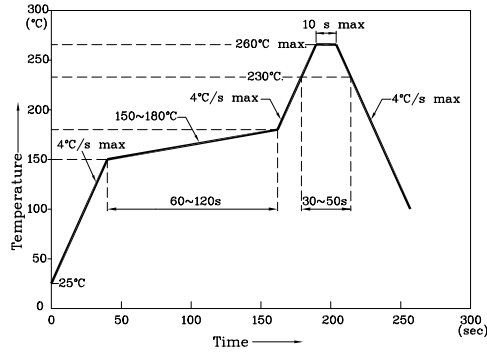
❖ DG





Reflow soldering is recommended and the soldering profile is shown below.
Other soldering methods are not recommended as they might cause damage to the product.

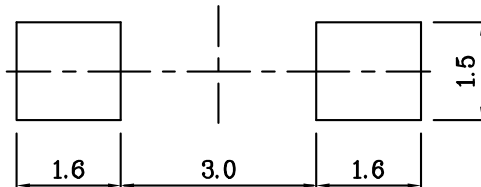
Reflow Soldering Profile For Lead-free SMT Process.



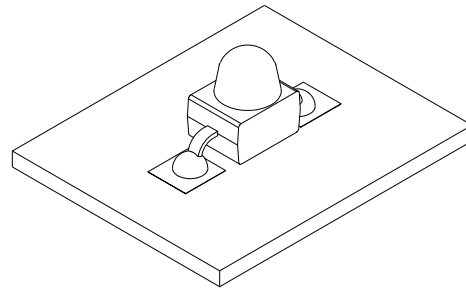
NOTES:

1. Maximum soldering temperature should not exceed 260°C.
2. Recommended reflow temperature: 145°C-260°C.
3. Do not put stress to the epoxy resin during high temperatures conditions.

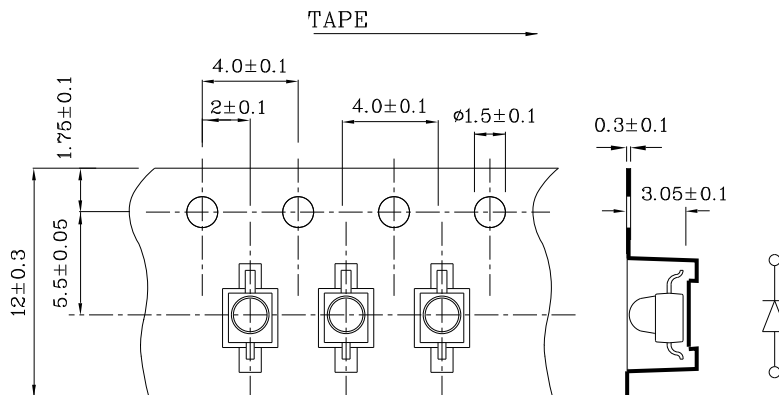
❖ **Recommended Soldering Pattern**
(Units : mm; Tolerance: ± 0.1)



❖ **The device has a single mounting surface. The device must be mounted according to the specifications.**



❖ **Tape Specification (Units : mm)**



Remarks:

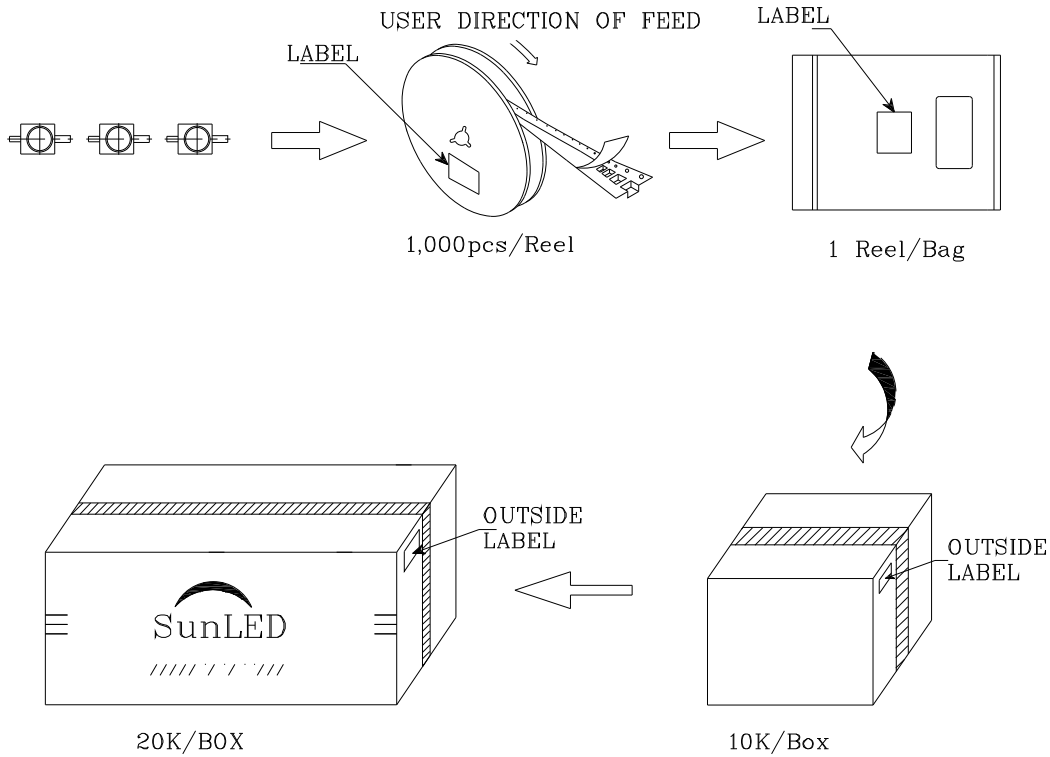

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V


Note: Accuracy may depend on the sorting parameters.

PACKING & LABEL SPECIFICATIONS

XZDG46W-3

Q.C. Q C	
XX	XX XXXX
PASSED	

P/NO : XZxxx46x-3	
QTY : 1,000 pcs	CODE: XXX
S/N : XX	
LOT NO :	
 XXXXXXXXXXXXXXXXXXXXXXXXXX	
RoHS Compliant	